Product Change Notification: BLAS-09GOSU780

Date:

14-Mar-2026

Product Category:

Memory

Notification Subject:

CCB 8129 and 8129.001 Final Notice: Qualification of ASSH as an additional assembly site and qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material, AMK-EP27 as a new die attach material and AMK-MC27 as a new mold compound material at ANAP assembly site for AT25080B-XHL-B, AT25080B-XHL-T, AT25160B-XHL-T and AT25160B-XHL-B catalog part numbers (CPN) available in 8L TSSOP (4.4mm) package.

Affected CPNs:

BLAS-09GOSU780_Affected_CPN_03142026.pdf
BLAS-09GOSU780_Affected_CPN_03142026.csv

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of ASSH as an additional assembly site and qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material, AMK-EP27 as a new die attach material and AMK-MC27 as a new mold compound material at ANAP assembly site for AT25080B-XHL-B, AT25080B-XHL-T, AT25160B-XHL-T and AT25160B-XHL-B catalog part numbers (CPN) available in 8L TSSOP (4.4mm) package.

Pre and Post Summary Changes:

	Pre Change	**Post Change**	**Change** (Yes/No)

Assembly Site	Amkor Technology Philippine (P1/P2), INC. (ANAP)	Amkor Technology Philippine (P1/P2), INC. (ANAP)	ATX Semiconductor (Shanghai)Co. Ltd (ASSH)	Yes
Wire Material	PdCu	CuPdAu	CuPdAu	Yes
Die Attach Material	8290 (PFAS)	AMK-EP27 (PFAS-free)	EN-4900GC (PFAS-free)	Yes
Molding Compound Material	G700A	AMK-MC27	G700LY	Yes
Lead-Frame Material	C7025	C7025	C7025	No
Lead-Frame Paddle Size	98 x 87 mils	98 x 87 mils	126 x 87 mils	Yes
Lead-Frame Lead-lock	No	Yes	Yes	Yes
Lead-Frame Drawing	See Pre and Post Change for Comparison.			
DAP Surface Prep	PPF	TPPF	PPF	Yes

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability and on-time delivery performance by qualifying of ASSH as an additional assembly site and qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material, AMK-EP27 as a new die attach material and AMK-MC27 as a new mold compound material at ANAP assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date: 30 April 2026 (date code: 2618)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	March 2026	April 2026

Work Week	10	11	12	13	14	15	16	17	18
Qual Report Availability		X							
Final PCN Issue Date		X							
Estimated First Ship Date									X

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: March 14, 2025: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PFAS Elimination and Die Attach_Explanation.pdf
PCN_BLAS-09GOSU780_Pre_and_Post_Change_Summary_.pdf
PCN_BLAS-09GOSU780 Qualification Report V1.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

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